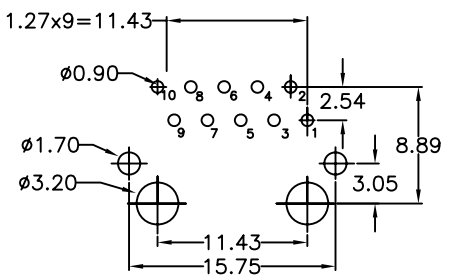
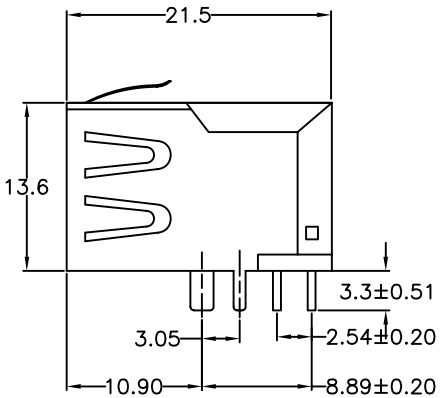
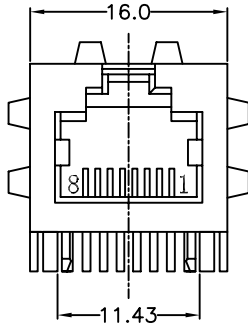
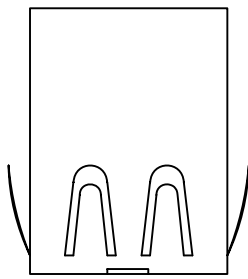


REV.	SPECIFICATION	ECN NO.	APPD.



P.C. Board Layout

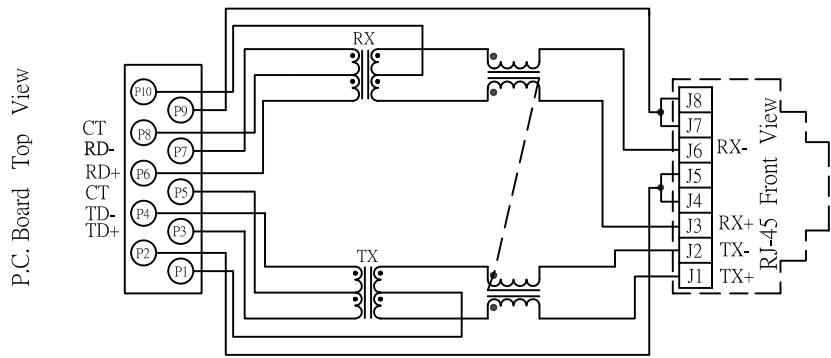
**Mechanicals**

**Housing:** High Temperature Plastic UL94V-0.  
**Insert:** Copper Alloy, Thermoplastic Polyester Glass Filled UL94V-0.  
**Plate:** Thermoplastic Polyester Glass Filled UL94V-0.  
**Contact Pin:** Copper Alloy.  
**Shielding:** Copper Alloy.

**Electrical Specifications@25° C:**

Turn Ratio(±5%): 1CT:1CT.  
 OCL(100KHz/0.1V@8mA): 350uH Min.  
 Insertion Loss(dB Max): -1.2dB(1-100MHz)  
**Return Loss(dB Min):**  
 -16dB(1-30MHz), -14dB(40MHz), -13dB(50MHz), -12dB(60-80MHz)  
**Cross Talk(dB Min):**  
 -45dB(30MHz), -40dB(60MHz), -35dB(100MHz)  
**DCMR(dB Min):**  
 -43dB(30MHz), -37dB(60MHz), -33dB(100MHz)  
 HI-Pot Test : 1500Vrms/0.5mA/2Sec.  
 Operating Temperature: 0° C~+70° C.

**\*RoHS Compliant**



8949-M 8 8 1 /06 S C 1 B A /A002  
 Series Position 8: 8 Contacts loaded 1: 1 Port 06: 6 μ" Gold Plated 15: 15 μ" Gold Plated 30: 30 μ" Gold Plated 50: 50 μ" Gold Plated  
 S: Shield 1: With Grounding B: Black A: Tray Package

<b>Tolerances</b>	<b>Drawn No.</b>	8949D02107	<b>Title:</b>		<b>OUPIN</b> OUPIN ELECTRONIC(KUNSHAN) CO., LTD. P/N: 8949-M881/06SC1BA/A002	
x = ±0.5	<b>Projection</b>		8949-M Series			
.x = ±0.35	<b>Unit</b>	mm	Rj-45 Modular Jack			
.xx = ±0.25	<b>Scale</b>	1:1	①560			
	<b>Drawn By</b>	Peggy 06/10'11	<b>SHEET</b>	1/1	<b>Ver.No.</b>	A4